

VT-47PP NF/LF

No Flow & Low Flow Prepreg

UL Approval: E214381 Version: B1

General Information

A generation of phenolic cured Low and No Flow products using Ventec's VT-47 resin technology with optimized resin rheology designed to enhance bond strength, specifically designed for lead free assembly processes. It has good bonding and thermal performance in heat sink bonding and rigid-flex board applications, and offers controlled flow ranges and constancy through the lamination process.

- > High Tg & High Td
- > Lead Free Compatible
- > IPC-4101E /97 /98 /99 /101 /126

Storage Condition & Shelf Life

| | | Prepreg | |
|----------------------|-------------------|---------------|--------------|
| Storage Condition | Temperature | < 23°C (73°F) | < 5°C (41°F) |
| | Relative humidity | < 55% | 1 |
| Shelf Life | | 3 months | 6 months |

The prepreg exceeding shelf life should be retested.

Availability

| Product | Туре | Glass Type | Resin Content | Flow Range (mil) | (mm) | Pressed Th (mil) | ickness (mm) |
|-----------|---------|------------|------------------|---------------------|-----------|---------------------|-----------------|
| VT-47 PP | 106 NF | 106 | 68% | 10~50 | 0.25~1.25 | 1.8 | 0.046 |
| Lead Free | 1080 NF | 1080 | 60% | 10~50 | 0.25~1.25 | 2.7 | 0.069 |
| Tg 170°C | 106 LF | 106 | 72% | 60~120 | 1.5~3 | 2.0 | 0.051 |
| | 1080 LF | 1080 | 65% | 60~120 | 1.5~3 | 3.0 | 0.076 |

- * Measured by micrometer "NF" ---- No Flow PP, "LF" ---- Low Flow PP
- 1) Press Temperature ---- 171°C
- 2) 3plys per pressing
- 3) Press Pressure ---- 200psi Built per IPC-TM-650 2.3.17.2

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Properties Sheet of Pressed No Flow Prepreg

| Test Item | | Test Method (IPC-TM-650) | Unit | VT-47 |
|---------------------------|--------------------|-----------------------------|--------|-------|
| Tg | TMA | 2.4.24 | °C | 170 |
| Td | TGA | ASTM D3850 | °C | 360 |
| Electric Strength | | 2.5.6.2 | KV/mm | 54 |
| Peel Strength with 1oz Cu | | 2.4.8 | Lb/in | 9-10 |
| Peel strength with CVL | | 2.4.8 | Lb/in | 6 |
| Moisture | D24/23 | 2.6.21 | % | 0.10 |
| Absorption | After PCT | 1atm., 121°C, 1hour | % | 0.12 |
| X,Y-axis CTE | 30~125°C | 2.4.24 | ppm/°C | 12~15 |
| Z-axis CTE | Before Tg | 2.4.24 | ppm/°C | 70 |
| | After Tg | | | 300 |
| Thermal Stress | Solder dip 288°C | 2.4.13.1 | Second | >300 |
| Breakdown Voltage | D48/50+ D0.5/23 | 2.5.6 | KV | >60 |
| Arc Resistance | D48/50+ D0.5/23 | 2.5.1 | Second | 120 |
| DK (RC60% at 1GHz) | C24/23/50 | 2.5.5.9 | - | 3.9 |
| DF (RC60% at 1GHz) | C24/23/50 | 2.5.5.9 | - | 0.017 |
| Flammability | As Received | UL94 | Rating | V-0 |

All test data provided are typical values and not intended to be specification values.

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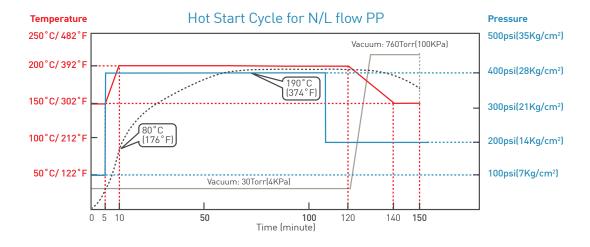
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Press Condition

| | VT-47PP | |
|---|----------------------------|--|
| Heating rate of materials | 3.0-5.0°C/min (5~10°F/min) | |
| Cure Temperature | ≥185°C | |
| Cure Time | >60min | |
| Vacuum should be continued until over 140°C (284°F) [Material Temperature] | | |
| Pressure on materials: Start with 100psi, Full pressure: 250~450psi | | |
| Cold Press: Keep Plate @ Room Temperature by water; Pressure: 100psi; Dwell Time: 60minutes | | |

Contact Ventec technical service to discuss the specific condition.



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